

MC74HC1G08

Single 2-Input AND Gate

The MC74HC1G08 is a high speed CMOS 2-input AND gate fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

The MC74HC1G08 output drive current is 1/2 compared to MC74HC series.

Features

- High Speed: $t_{PD} = 7 \text{ ns}$ (Typ) at $V_{CC} = 5 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \text{ }\mu\text{A}$ (Max) at $T_A = 25^\circ\text{C}$
- High Noise Immunity
- Balanced Propagation Delays ($t_{pLH} = t_{pHL}$)
- Symmetrical Output Impedance ($I_{OH} = I_{OL} = 2 \text{ mA}$)
- Chip Complexity: FET = 44
- Pb-Free Packages are Available

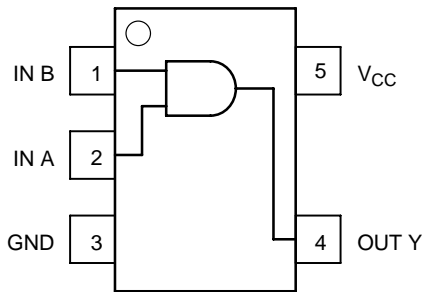


Figure 1. Pinout

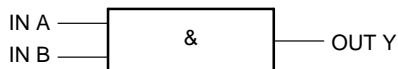


Figure 2. Logic Symbol



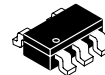
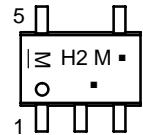
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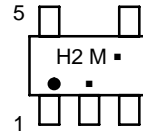
MARKING DIAGRAMS



SC-88A / SOT-353 / SC-70
DF SUFFIX
CASE 419A



TSOP-5 / SOT-23 / SC-59
DT SUFFIX
CASE 483



H2 = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

PIN ASSIGNMENT	
1	IN B
2	IN A
3	GND
4	OUT Y
5	V _{CC}

FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

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MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	- 0.5 to + 7.0	V
V_{IN}	DC Input Voltage	- 0.5 to $V_{CC} + 0.5$	V
V_{OUT}	DC Output Voltage	- 0.5 to $V_{CC} + 0.5$	V
I_{IK}	DC Input Diode Current	± 20	mA
I_{OK}	DC Output Diode Current	± 20	mA
I_{OUT}	DC Output Sink Current	± 12.5	mA
I_{CC}	DC Supply Current per Supply Pin	± 25	mA
T_{STG}	Storage Temperature Range	- 65 to + 150	$^{\circ}C$
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	$^{\circ}C$
T_J	Junction Temperature Under Bias	+ 150	$^{\circ}C$
θ_{JA}	Thermal Resistance	SC70-5/SC-88A/SOT-353 (Note 1) SOT23-5/TSOP-5/SC59-5 350 230	$^{\circ}C/W$
P_D	Power Dissipation in Still Air at 85 $^{\circ}C$	SC70-5/SC-88A/SOT-353 SOT23-5/TSOP-5/SC59-5 150 200	mW
MSL	Moisture Sensitivity	Level 1	
F_R	Flammability Rating	Oxygen Index: 28 to 34 UL 94 V-0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4) > 2000 > 200 N/A	V
$I_{LATCHUP}$	Latchup Performance	Above V_{CC} and Below GND at 125 $^{\circ}C$ (Note 5) ± 500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 20 ounce copper trace with no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V_{CC}	DC Supply Voltage	2.0	6.0	V	
V_{IN}	DC Input Voltage	0.0	V_{CC}	V	
V_{OUT}	DC Output Voltage	0.0	V_{CC}	V	
T_A	Operating Temperature Range	- 55	+ 125	$^{\circ}C$	
t_r, t_f	Input Rise and Fall Time	$V_{CC} = 2.0 V$ $V_{CC} = 3.0 V$ $V_{CC} = 4.5 V$ $V_{CC} = 6.0 V$	0 0 0 0	1000 600 500 400	ns

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature $^{\circ}C$	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

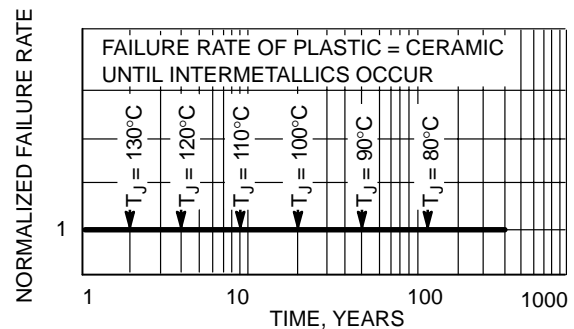


Figure 3. Failure Rate vs. Time Junction Temperature

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DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CC} (V)	T _A = 25°C			T _A ≤ 85°C		-55°C ≤ T _A ≤ 125°C		Unit		
				Min	Typ	Max	Min	Max	Min	Max			
V _{IH}	Minimum High-Level Input Voltage		2.0	1.5			1.5		1.5		V		
			3.0	2.1			2.1		2.1				
			4.5	3.15			3.15		3.15				
			6.0	4.20			4.20		4.20				
V _{IL}	Maximum Low-Level Input Voltage		2.0			0.5		0.5		0.5	V		
			3.0			0.9		0.9		0.9			
			4.5			1.35		1.35		1.35			
			6.0			1.80		1.80		1.80			
V _{OH}	Minimum High-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	V _{IN} = V _{IH} or V _{IL} I _{OH} = -20 μA	2.0	1.9	2.0		1.9		1.9		V		
			3.0	2.9	3.0		2.9		2.9				
			4.5	4.4	4.5		4.4		4.4				
			6.0	5.9	6.0		5.9		5.9				
		V _{IN} = V _{IH} or V _{IL} I _{OH} = -2 mA I _{OH} = -2.6 mA	4.5	4.18	4.31		4.13		4.08				
			6.0	5.68	5.80		5.63		5.58				
V _{OL}	Maximum Low-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	V _{IN} = V _{IH} or V _{IL} I _{OL} = 20 μA	2.0		0.0	0.1		0.1		0.1	V		
			3.0		0.0	0.1		0.1		0.1			
			4.5		0.0	0.1		0.1		0.1			
			6.0		0.0	0.1		0.1		0.1			
		V _{IN} = V _{IH} or V _{IL} I _{OL} = 2 mA I _{OL} = 2.6 mA	4.5		0.17	0.26		0.33		0.40			
			6.0		0.18	0.26		0.33		0.40			
I _{IN}	Maximum Input Leakage Current	V _{IN} = 6.0 V or GND	6.0			±0.1		±1.0		μA			
I _{CC}	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND	6.0			1.0		10		μA			

AC ELECTRICAL CHARACTERISTICS (Input t_r = t_f = 6.0 ns)

Symbol	Parameter	Test Conditions	T _A = 25°C			T _A ≤ 85°C		-55°C ≤ T _A ≤ 125°C		Unit	
			Min	Typ	Max	Min	Max	Min	Max		
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input A or B to Y	V _{CC} = 5.0 V C _L = 15 pF		3.5	15		20		25	ns	
				20	100		125		155		
		V _{CC} = 2.0 V C _L = 50 pF		11	27		35		90		
			V _{CC} = 3.0 V		8	20		25			35
			V _{CC} = 4.5 V		7	17		21			26
t _{TLH} , t _{THL}	Output Transition Time	V _{CC} = 5.0 V C _L = 15 pF		3	10		15		20	ns	
				25	125		155		200		
		V _{CC} = 2.0 V C _L = 50 pF		16	35		45		60		
			V _{CC} = 3.0 V		11	25		31			38
			V _{CC} = 4.5 V		9	21		26			32
C _{IN}	Maximum Input Capacitance			5	10		10		10	pF	

C _{PD}	Power Dissipation Capacitance (Note 6)	Typical @ 25°C, V _{CC} = 5.0 V		pF
		10		

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

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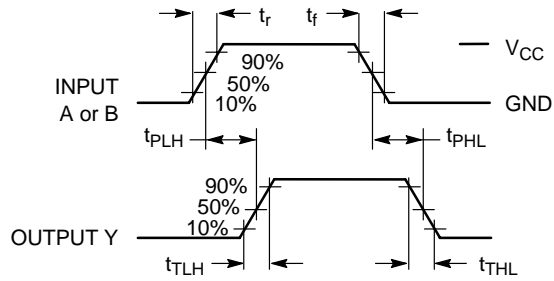
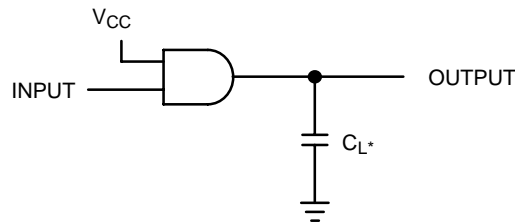


Figure 4. Switching Waveforms



*Includes all probe and jig capacitance.
A 1-MHz square input wave is recommended for propagation delay tests.

Figure 5. Test Circuit

ORDERING INFORMATION

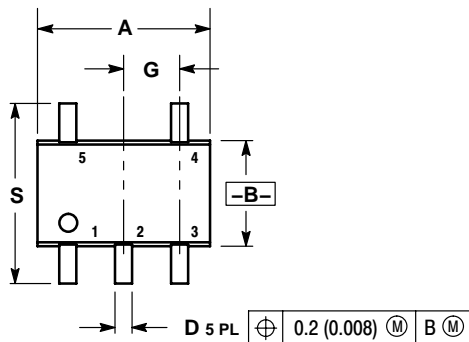
Device	Package	Shipping†
MC74HC1G08DFT1	SC70-5/SC-88A/SOT-353	3000 / Tape & Reel
MC74HC1G08DFT1G	SC70-5/SC-88A/SOT-353 (Pb-Free)	
MC74HC1G08DFT2	SC70-5/SC-88A/SOT-353	
MC74HC1G08DFT2G	SC70-5/SC-88A/SOT-353 (Pb-Free)	
MC74HC1G08DTT1	SOT23-5/TSOP-5/SC59-5	
MC74HC1G08DTT1G	SOT23-5/TSOP-5/SC59-5 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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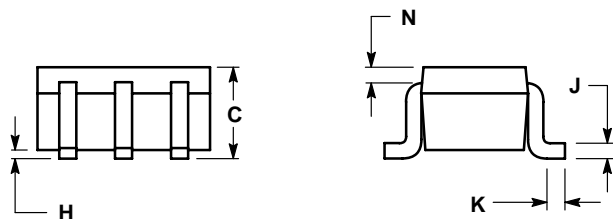
PACKAGE DIMENSIONS

SC-88A, SOT-353, SC-70
CASE 419A-02
ISSUE J

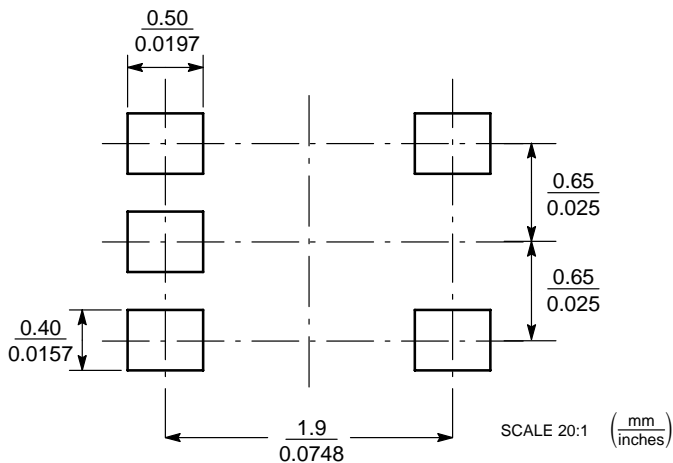


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20



SOLDERING FOOTPRINT*

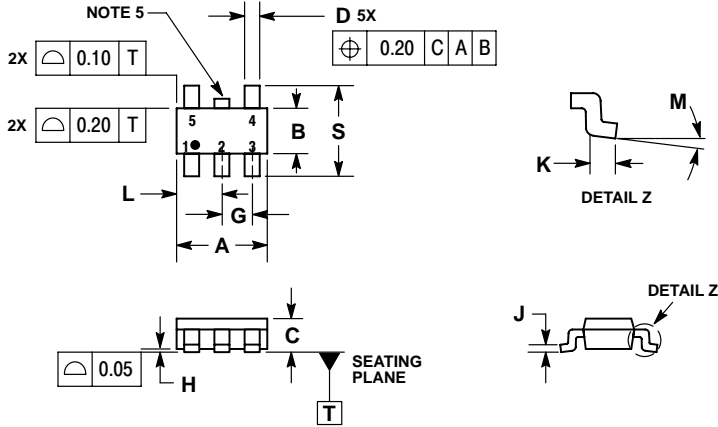


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

TSOP-5 CASE 483-02 ISSUE G

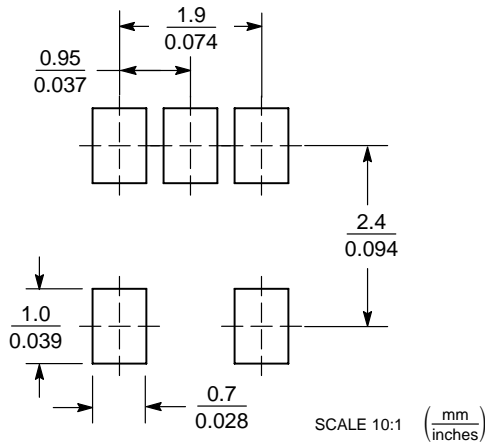


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

DIM	MILLIMETERS	
	MIN	MAX
A	3.00 BSC	
B	1.50 BSC	
C	0.90	1.10
D	0.25	0.50
G	0.95 BSC	
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
L	1.25	1.55
M	0°	10°
S	2.50	3.00

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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